

AMENDMENTS TO THE SPECIFICATION:

Please replace the paragraph beginning at page 16, line 22 with the following amended paragraph:

Next, a ~~forth~~ fourth embodiment according to the present invention will be described with reference to the drawings. Fig. 4 is a schematic side sectional view showing the configuration of an optoelectronic hybrid integrated module according to the ~~forth~~ fourth embodiment having such a configuration that an optical axis converter is provided at the light extracting part of the present invention.

Please replace the paragraph beginning at page 17, line 20 with the following amended paragraph:

Next, a fifth embodiment according to the present invention will be described with reference to the drawings. Fig. 5 is a schematic side sectional view showing the configuration of an optoelectronic hybrid integrated module according to the fifth embodiment in which the transparent base material of the present invention consists of a flexible sheet. The configurations of a light extracting part 54, an optical device 51 and a driver IC 52 are same as those of the first to the ~~forth~~ fourth embodiments.

Please replace the paragraph beginning at page 18, line 22 with the following amended paragraph:

The interposer may be provided to an optoelectronic hybrid integrated module having a transparent plate as a transparent base material described in the first to the ~~forth~~ fourth

embodiments. The configurations and the operations are same as that of the first embodiment except that the transparent base material consists of a flexible sheet and an interposer having heat dissipating and holding functions is provided, therefore the explanations are omitted.

Please replace the paragraph beginning at page 19, line 11 with the following amended paragraph:

Around the lower side of the transparent plate 63, a holding frame 68 having interlayer wiring 69 is mounted, surrounding an optical device 61 and a driver IC 62. However, light extracting is same as that of the first to the ~~forth~~ fourth embodiments, like the fifth embodiment.

Please replace the paragraph beginning at page 21, line 19 with the following amended paragraph:

Although the optoelectronic hybrid integrated module 5 of the fifth embodiment using a flexible sheet has been described as the optoelectronic hybrid integrated module 101, optoelectronic hybrid integrated modules according to the first to the ~~forth~~ fourth and the sixth embodiments may be used, and the connection between optoelectronic hybrid integrated modules and the logic LSI may be performed with a metal wire or electrodes in the substrate 104.